Compliant with IEC 62474/ D9.00

MICROCHIP Semiconductor Device Type: P (G6X) 020 PDIP .300in Matte Tin				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials			
Semiconductor Device Type.		"Contained In"	% Total		1					e3
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	1207.29	(mg) Total	Mold Compound	% ot Total Weight	79.8
Fused Silica	60676-86-0	Mold Compound	57.456	869.252	574,560		Fused Silica	60676-86-0	72.00	
Metal Hydro Oxide	Trade Secret	Mold Compound	8.778	132.802	87,780		Metal Hydro Oxide	Trade Secret	11.00	
Epoxy Resin	Trade Secret	Mold Compound	5,586	84.511	55,860		Epoxy Resin	Trade Secret	7.00	
Phenol Resin	Trade Secret	Mold Compound	5.586	84.511	55,860		Phenol Resin	Trade Secret	7.00	1
SiO2	14808-60-7	Mold Compound	1.995	30.182	19,950		SiO2	14808-60-7	2.50	
Carbon Black	1333-86-4	Mold Compound	0.399	6.036	3,990		Carbon Black	1333-86-4	0.50	
Copper	7440-50-8	Lead Frame	10.031	151.766	100.314			Total	100.00	_
Iron	7439-89-6	Lead Frame	0.247	3.733	2,468	158.85	(mg) Total	Lead Frame	% of Total Weight	10.5
Silver	7440-22-4	Lead Frame	0.200	3.026	2,000	130.03		7440-50-8	95.54	10.5
Zinc	7440-66-6	Lead Frame	0.200	0.199	131		Copper	7440-50-8	2.35	
							Iron			
Phosphorous	7723-14-0	Lead Frame	0.009	0.131	87		Silver	7440-22-4	1.91	
Silver	7440-22-4	Die Attach	0.550	8.324	5,502		Zinc	7440-66-6	0.13	
Epoxy Resin	9003-36-5	Die Attach	0.110	1.665	1,100		Phosphorous	7723-14-0	0.08	
Diluent	3101-60-8	Die Attach	0.055	0.832	550			Total	100.00	
Phenolic hardener	Trade secret	Die Attach	0.022	0.332	220	11.35	(mg) Total	Die Attach	% of Total Weight	0.75
Amine type hardener	827-43-0	Die Attach	0.011	0.167	110		Silver	7440-22-4	73.36	
Dicyandiamide	461-58-5	Die Attach	0.002	0.027	18		Epoxy Resin	9003-36-5	14.67	1
Silicon	7440-21-3	Chip (Die)	7.500	113,468	75.000		Diluent	3101-60-8	7.33	
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	0.197	2.973	1,965		Phenolic hardener	Trade secret	2.93	1
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.004	0.053	35		Amine type hardener	827-43-0	1.47	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	18.911	12.500		Dicyandiamide	461-58-5	0.24	
****	7110010	TOTALS:	100.000	1,512.900	1.000.000		Dicyandianniac	Total		
	4 5400	g Total Mass		1,012.000	.,000,000	113.47	Total (mg)	Chip (Die)	% of Total Weight	
is semiconductor device and its homogenous materials comply w		2002/95/EC (27 January 2003) & Directive 2011/65/EU (08	luno 2011\ ar	1 0045/000/51	1 /04 84					
	. ,	le cumplior declarations and for analytical test data	o oune 2011) ai	id 2015/863/EU	J (31 March		Doped Silicon	7440-21-3	100.00]
ompliance with the above EU Directives has been verified via interra a chemical substance is absent from the list above, the chemical s corporated's knowledge and belief as of the date of this document.	nal design contro ubstance is NOT , there is no credi	an intentional ingredient in the semiconductor device and, ble reason to believe that the unavoidable impurity concer	to the best of	Microchip Teo	chnology	3.03	Doped Silicon	7440-21-3 Total Wire Bond Copper palladium coated (CuPd)	100.00 100.00 % of Total Weight	0.2
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